



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. Musser

Filed: December 12, 2000

For: **METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND
THE LIKE**

EXCESS CLAIM FEE PAYMENT LETTER

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

An Amendment Under 37 C.F.R. § 1.116 is attached hereto for concurrent filing in the above-identified application. The resulting excess claim fee has been calculated as shown below:

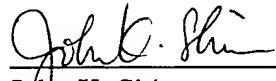
	After Amendment	Highest No. Previously Paid For	
All Claims	30	-	20 = 10 X \$18.00 = \$180.00
Independent	2	-	3 = 3 X \$88.00 = \$0.00
Multiple Dependent Claim Fee			= \$300.00
		TOTAL	= \$480.00

EXCESS CLAIM FEE PAYMENT LETTER
U.S. Application No. 09/719,422

Q62228

A check for the statutory fee of \$480.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this letter is enclosed.

Respectfully submitted,



John K. Shin
Registration No. 48,409

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE
23373
CUSTOMER NUMBER

Date: October 1, 2004



IFC
RCE \$

**REQUEST
FOR
CONTINUED EXAMINATION (RCE)
TRANSMITTAL**

MAIL STOP RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Subsection (b) of 35 U.S.C. § 132, effective on May 29, 2000,
provides for continued examination of an utility or
plant application filed on or after June 8, 1995

Application Number	09/719,422
Confirmation Number	7788
Filing Date	December 12, 2000
First Named Inventor	Yoshihisa FURUTA
Group Art Unit	1733
Examiner Name	Barbara J. Musser
Matter Number	Q62228
Title	METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND THE LIKE

This is a Request for Continued Examination (RCE) under 37 C.F.R. § 1.114 of the above-identified application.

1. SUBMISSION REQUIRED UNDER 37 C.F.R. § 1.114

a. Previously submitted
i. Please enter and consider the amendment(s)/reply under 37 C.F.R. § 1.116
previously filed on _____
ii. Consider the arguments in the Appeal Brief or Reply Brief previously filed on _____
iii. Other _____

b. Enclosed
i. Amendment under 37 C.F.R. § 1.114(c) 10/04/2004 SSESHE1 00000009 09719422
ii. Affidavit(s)/Declaration(s) 01 FC:1801 790.00 OP
iii. Information Disclosure Statements (IDS)
iv. Petition for Extension of Time
v. Other _____

2. MISCELLANEOUS

a. Suspension of action on the above-identified application is requested under 37 C.F.R. § 1.103(c) for a period of _____ months
b. Other _____

3. FEES

A check for the RCE statutory fee of \$790.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this transmittal letter is attached.

CORRESPONDENCE ADDRESS

Direct all correspondence to the address for SUGHRUE MION, PLLC filed under the Customer Number listed below:

WASHINGTON OFFICE
23373
CUSTOMER NUMBER

SIGNATURE OF ATTORNEY

Name John K. Shin Registration No. 48,409
Signature John K. Shin Date October 1, 2004



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Confirmation No.: 7788

Group Art Unit: 1733

Filed: December 12, 2000

Examiner: Barbara J. Musser

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND
THE LIKE

AMENDMENT UNDER 37 C.F.R. § 1.114(c)

MAIL STOP RCE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated July 6, 2004, please amend the above-identified application as follows on the accompanying pages.

TABLE OF CONTENTS

AMENDMENTS TO THE CLAIMS	2
REMARKS	6

10/04/2004 SSESHE1 0000009 09719422

02 FC:1202
03 FC:1203

180.00 0P
300.00 0P